

Features

- High power ratings with higher hold currents at elevated temperatures
- Operating temperature range from -40 °C to 125 °C
- Low thermal derating factor
- Standard 1812 footprint size
- Compliant with AEC-Q200 Rev-D Stress Test Qualification for Passive Components in automotive applications
- Surface mount packaging for automated assembly
- Agency recognition: c sus
- RoHS compliant*



MF-MSHT Series – PTC Resettable Fuses

Additional Information

Click these links for more information:













SAMPLES

Electrical Characteristics

	V _{max}	I _{max}	l _{hold}	I _{trip}	Res	istance	Max. Time To Trip		Tripped Power Dissipation	Agency Recognition		AEC-Q200 Compliant
Model	IIIax	Illax	at 2:	3 °C		at 23 °C Ohms		23 °C	at 23 °C Watts	cUL TÜV		
	Volts	Amps	Am	nps	R _{Min} .	R _{1Max.**}	Amps	Seconds	Typical	E174545	R 50384138	
MF-MSHT020KX	42	40	0.20	1.0	0.5	4.5	8.0	0.1	1.2	✓	1	1
MF-MSHT035KX	36	40	0.35	1.75	0.3	2.6	8.0	0.1	1.2	✓	1	/
MF-MSHT050KX	30	40	0.50	2.5	0.18	1.6	8.0	0.1	1.2	✓	1	1
MF-MSHT075KX	30	40	0.75	3.75	0.09	0.85	8.0	5.0	1.5	✓	1	1
MF-MSHT110KX	16	40	1.10	5.5	0.05	0.45	8.0	5.0	1.5	✓	1	1
MF-MSHT125KX	9	40	1.25	6.25	0.03	0.30	8.0	5.0	1.5	✓	pending	1
MF-MSHT150KX	9	40	1.50	6.0	0.022	0.20	10.0	5.0	1.5	1	pending	1
MF-MSHT175KX	9	40	1.75	7.0	0.018	0.17	10.0	5.0	1.5	✓	pending	✓

^{**}R_{1Max.} measured 24 hours post reflow

Environmental Characteristics

Item	Condition	Criteria
Operating Temperature	-40 °C to +125 °C	
Recommended Storage	+40 °C max. / 70 % R.H. max.	
Passive Aging	+125 °C, 1000 hours	$R < R_{1max}$
Humidity Aging	+85 °C, 85 % R.H. 1000 hours	$R < R_{1max}$
Thermal Shock	-40 °C to +125 °C, 20 times	$R < R_{1max}$
Solvent Resistance	MIL-STD-202, Method 215	No change (marking still legible)
Vibration	MIL-STD-883C, Method 2007.1 Condition A	No change (R _{min} < R < R _{1max})
Moisture Sensitivity Level (MSL)	See Note	
ESD Classification	Class 6 (per AEC-Q200-2, HBM)	

Test Procedures and Requirements

Item	Test Condition	Accept/Reject Criteria
Visual/Mechanical	Verify dimensions and materials	Per MF physical description
Resistance	In still air @ 23 °C	$R_{min} \le R \le R_{max}$
Time to Trip	At specified current, V _{max} , 23 °C, still air	T ≤ max. time to trip (seconds)
Hold Current	30 min. at I _{hold} , still air	No trip
Trip Cycle Life	V _{max} , I _{max} , 100 cycles	No arcing or burning
Trip Endurance	V _{max} , 48 hours	No arcing or burning
Solderability	245 °C ±5 °C, 5 seconds	95 % min. coverage

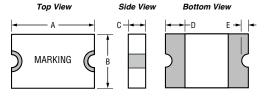
Applications

- Overcurrent surge protection of electronic equipment required to operate at high operating temperature ranges
- Robust resettable fault protection for industrial transportation, communication, security, and consumer electronic equipment

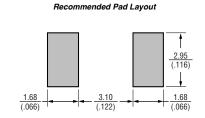
MF-MSHT Series – PTC Resettable Fuses

BOURNS

Product Dimensions



Terminal Material: ENIG-plated terminals

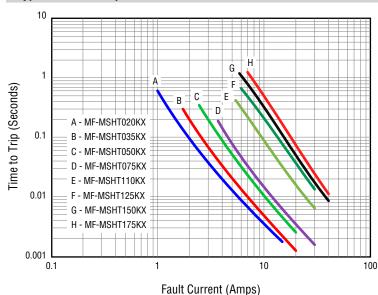


Model		A	E	3	С		D	E
Wodei	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
MF-MSHT020KX								
MF-MSHT035KX	4.37	4.83	3.07	3.41	0.40	0.85		
MF-MSHT050KX	4.37 (.172)	(.190)	3.07 (.121)	3.41 (.134)	<u>0.40</u> (.016)	(.033)		
MF-MSHT075KX							0.30	0.05
MF-MSHT110KX	4.37 (.172)	<u>4.83</u> (.190)	3.07 (.121)	3.41 (.134)	<u>0.60</u> (.024)	1.20 (.047)	<u>0.30</u> (.012)	<u>0.05</u> (.002)
MF-MSHT125KX								
MF-MSHT150KX	4.37 (.172)	4.83 (.190)	3.07 (.121)	3.41 (.134)	<u>0.80</u> (.031)	1.60 (.063)		
MF-MSHT175KX								

Thermal Derating Table - Ihold (Amps)

Model	Ambient Operating Temperature									
Wodei	-40 °C	-20 °C	0 °C	+23 °C	+40 °C	+50 °C	+60 °C	+70 °C	+85 °C	+125 °C
MF-MSHT020KX	0.29	0.26	0.23	0.20	0.18	0.16	0.15	0.13	0.11	0.05
MF-MSHT035KX	0.51	0.46	0.41	0.35	0.31	0.28	0.26	0.23	0.20	0.09
MF-MSHT050KX	0.73	0.66	0.58	0.50	0.44	0.41	0.37	0.34	0.28	0.14
MF-MSHT075KX	1.09	0.98	0.87	0.75	0.66	0.61	0.56	0.50	0.42	0.20
MF-MSHT110KX	1.60	1.44	1.28	1.10	0.97	0.89	0.81	0.74	0.62	0.30
MF-MSHT125KX	1.81	1.64	1.45	1.25	1.10	1.01	0.93	0.84	0.70	0.34
MF-MSHT150KX	2.18	1.97	1.74	1.50	1.32	1.22	1.11	1.01	0.84	0.41
MF-MSHT175KX	2.54	2.29	2.03	1.75	1.54	1.42	1.30	1.17	0.98	0.47

Typical Time to Trip at 23 °C



The Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.

MF - MSHT 035 K X - 2 Multifuse® Product Designator Series MSHT = 1812 High Temperature Surface Mount Component Hold Current, I_{hold} 020 - 175 (0.2 - 1.75 Amps) K = Material Specific Code X = Multifuse® freeXpansion™ Design Packaging

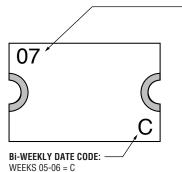
-2 = Tape and Reel Packaged per EIA-481

Packaging Quantity

Model	Packaging Quantity
MF-MSHT020KX	2,000 pcs. per reel
MF-MSHT035KX	2,000 pcs. per reel
MF-MSHT050KX	2,000 pcs. per reel
MF-MSHT075KX	2,000 pcs. per reel
MF-MSHT110KX	1,500 pcs. per reel
MF-MSHT125KX	1,000 pcs. per reel
MF-MSHT150KX	1,500 pcs. per reel
MF-MSHT175KX	1,500 pcs. per reel

Typical Part Marking

Represents total content. Layout may vary.



PART IDENTIFICATION:

MF-MSHT020KX = 02 MF-MSHT035KX = 03 MF-MSHT050KX = 05 MF-MSHT075KX = 07 MF-MSHT110KX = 11 MF-MSHT125KX = 12

MF-MSHT125KX = 12 MF-MSHT150KX = 15

MF-MSHT175KX = 17

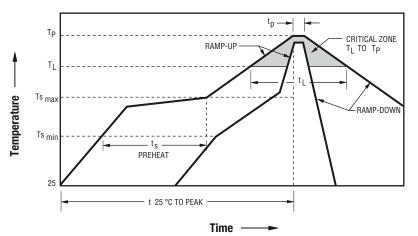
Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

MF-MSHT Series – PTC Resettable Fuses

BOURNS

Solder Reflow Recommendations



Notes:

- MF-MSHT models are intended for reflow soldering (including, but not limited to heating plate, hot air, IR, nitrogen, and vapor phase).
- Wave soldering is permissible only if the device is on the top of the PCB, opposite the heat source.
- · Hand soldering is not recommended for these devices.
- All temperatures refer to the topside of the device, measured on the device body surface.
- If reflow temperatures exceed the recommended profile, devices may not meet the published specifications.
- · Compatible with Pb and Pb-free solder reflow profiles.
- · Excess solder may cause a short circuit.
- Please refer to the <u>Multifuse</u> <u>Polymer PTC Resettable Fuse</u> <u>Soldering Recommendations</u> document for more details.

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Ts _{max} to T _p)	3 °C / second max.
PREHEAT:	
Temperature Min. (Ts _{min})	150 °C
Temperature Max. (Ts _{max})	200 °C
Time (Ts _{min} to Ts _{max}) (ts)	60~180 seconds
TIME MAINTAINED ABOVE:	
Temperature (T _L)	217 °C
Time (t _L)	60~150 seconds
Peak Temperature (T _p)	260 °C
Time within 5 °C of Actual Peak Temperature (tp)	20~40 seconds
Ramp-Down Rate	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

BOURNS®

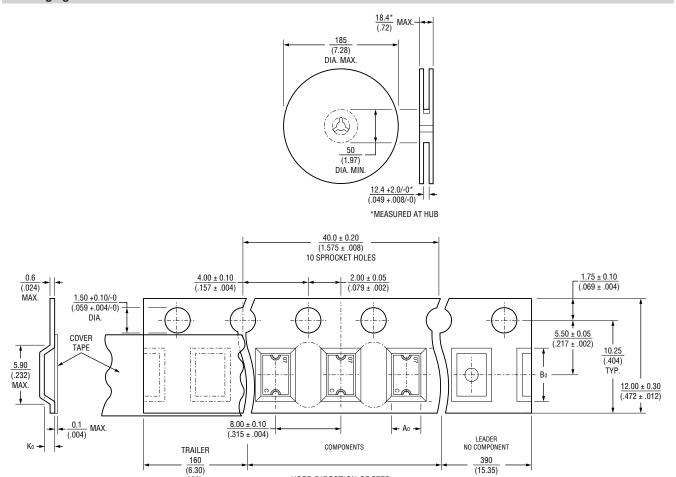
Asia-Pacific: Tel: +886-2 2562-4117 • Email: asiacus@bourns.com

EMEA: Tel: +36 88 885 877 • Email: eurocus@bourns.com

The Americas: Tel: +1-951 781-5500 • Email: americus@bourns.com

www.bourns.com

Packaging Dimensions



Model	A 0	Bo	K ₀	
MF-MSHT020KX ~ MF-MSHT075KX	$\frac{3.66 \pm 0.15}{(.144 \pm .006)}$	$\frac{4.98 \pm 0.10}{(.196 \pm .004)}$	$\frac{0.95 \pm 0.10}{(.037 \pm .004)}$	
MF-MSHT110KX	$\frac{3.58 \pm 0.10}{(.141 \pm .004)}$	$\frac{4.93 \pm 0.10}{(.194 \pm .004)}$	$\frac{1.30 \pm 0.10}{(.051 \pm .004)}$	
MF-MSHT125KX	$\frac{3.50 \pm 0.10}{(.138 \pm .004)}$	$\frac{4.90 \pm 0.10}{(.193 \pm .004)}$	$\frac{1.80 \pm 0.10}{(.071 \pm .004)}$	
MF-MSHT150KX ~ MF-MSHT175KX	$\frac{3.70 \pm 0.10}{(.146 \pm .004)}$	$\frac{5.10 \pm 0.10}{(.201 \pm .004)}$	$\frac{1.50 \pm 0.10}{(.059 \pm .004)}$	

USER DIRECTION OF FEED

MIN.

DIMENSIONS: $\frac{MM}{(INCHES)}$

Bourns® Multifuse® PPTC Resettable Fuses

BOURNS

Application Notice

- Users are responsible for independent and adequate evaluation of Bourns® Multifuse® Polymer PTC devices in the user's application, including the PPTC device characteristics stated in the applicable data sheet.
- Polymer PTC devices must not be allowed to operate beyond their stated maximum ratings. Operation in excess of such
 maximum ratings could result in damage to the PTC device and possibly lead to electrical arcing and/or fire. Circuits with
 inductance may generate a voltage above the rated voltage of the polymer PTC device and should be thoroughly evaluated
 within the user's application during the PTC selection and qualification process.
- Polymer PTC devices are intended to protect against adverse effects of temporary overcurrent or overtemperature
 conditions up to rated limits and are not intended to serve as protective devices where overcurrent or overvoltage conditions
 are expected to be repetitive or prolonged.
- In normal operation, polymer PTC devices experience thermal expansion under fault conditions. Thus, a polymer PTC
 device must be protected against mechanical stress, and must be given adequate clearance within the user's application to
 accommodate such thermal expansion. Rigid potting materials or fixed housings or coverings that do not provide adequate
 clearance should be thoroughly examined and tested by the user, as they may result in the malfunction of polymer PTC
 devices if the thermal expansion is inhibited.
- Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of polymer PTC devices.
- Aggressive solvents may adversely affect the performance of polymer PTC devices. Conformal coating, encapsulating, potting, molding, and sealing materials may contain aggressive solvents including but not limited to xylene and toluene, which are known to cause adverse effects on the performance of polymer PTCs. Such aggressive solvents must be thoroughly cured or baked to ensure their complete removal from polymer PTCs to minimize the possible adverse effect on the device.
- Recommended storage conditions should be followed at all times. Such conditions can be found on the applicable data sheet and on the Multifuse® Polymer PTC Moisture/Reflow Sensitivity Classification (MSL) note: https://www.bourns.com/docs/RoHS-MSL/msl_mf.pdf